LN1261CTR

Surface Mounting Chip LED

GW Type

Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit				
Power dissipation	P _D	60	mW				
Forward current	I _F	20	mA				
Pulse forward current *	I _{FP}	60	mA				
Reverse voltage	V _R	4	V				
Operating ambient temperature	T _{opr}	-25 to +80	°C				
Storage temperature	T _{stg}	-30 to +85	°C				

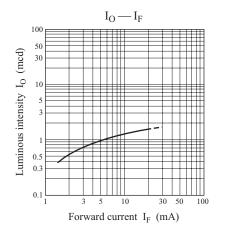
Lighting Color

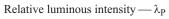
• Red

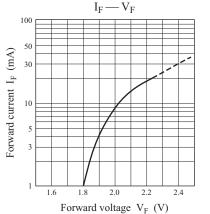
Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

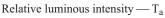
Electro-Optical Characteristics $T_a = 25^{\circ}C$

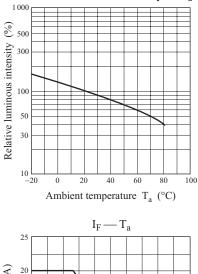
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity	I _O	$I_F = 15 \text{ mA}$	0.5	1.4		mcd
Reverse current	I _R	$V_R = 4 V$			10	μΑ
Forward voltage	V _F	$I_{\rm F} = 20 {\rm mA}$		2.2	2.8	V
Peak emission wavelength	$\lambda_{\rm P}$	$I_{\rm F} = 20 {\rm mA}$		700		nm
Spectral half band width	Δλ	$I_{\rm F} = 20 {\rm mA}$		100		nm

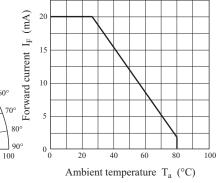












600

Peak emission wavelength λ_P (nm)

700

100

80

60

40

20

0∟ 500

Relative luminous intensity (%)

0 20 40 60 80

Relative luminous intensity (%)

Directive characteristics

0° 10

20

20° 10

30

60' 70°/

80 60 40

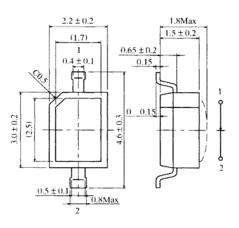
80°

800 100

LN1261CTR

Package (Unit: mm)





• Pin name

1: Anode

2: Cathode

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